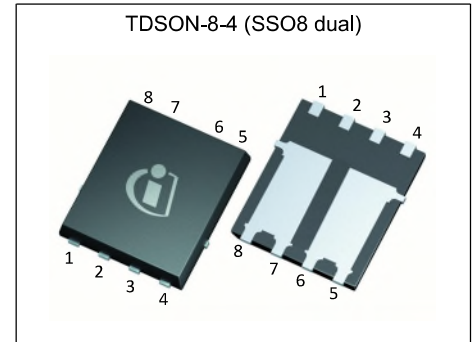


# MOSFET

## OptiMOS™-T2 Power Transistor, 60 V

### Features

- Dual N-channel, Logic level
- Fast switching MOSFETs for SMPS
- Optimized technology for Synchronous Rectification
- Pb-free plating; RoHS compliant
- 100% Avalanche tested
- Superior Thermal Resistance
- Halogen-free according to IEC61249-2-21

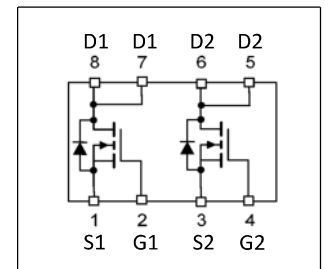


### Product validation

Fully qualified according to JEDEC for Industrial Applications

**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS}$	60	V
$R_{DS(on),max}$	11.2	mΩ
$I_D$	57	A



RoHS

Type / Ordering Code	Package	Marking	Related Links
BSC112N06LD	PG-TDSON-8-4	112N06LD	-

## Table of Contents

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## 1 Maximum ratings

at  $T_A=25\text{ °C}$ , unless otherwise specified, one transistor active

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$	-	-	57	A	$V_{GS}=10\text{ V}$ , $T_C=25\text{ °C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-	-	228	A	$T_A=25\text{ °C}$
Avalanche energy, single pulse <sup>3)</sup>	$E_{AS}$	-	-	80	mJ	$I_D=10\text{ A}$ , $R_{GS}=25\text{ }\Omega$
Gate source voltage	$V_{GS}$	-16	-	16	V	-
Power dissipation	$P_{tot}$	-	-	65	W	$T_C=25\text{ °C}$
Operating and storage temperature	$T_j, T_{stg}$	-55	-	175	°C	IEC climatic category; DIN IEC 68-1: 55/175/56

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	$R_{thJC}$	-	-	2.3	°C/W	-
Device on PCB, 6 cm <sup>2</sup> cooling area <sup>4)</sup>	$R_{thJA}$	-	-	60	°C/W	-
Device on PCB, minimal footprint <sup>5)</sup>	$R_{thJA}$	-	-	100	°C/W	-

<sup>1)</sup> Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

<sup>2)</sup> See Diagram 3 for more detailed information

<sup>3)</sup> See Diagram 13 for more detailed information

<sup>4)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

<sup>5)</sup> device mounted on a minimum pad (one layer, 70 µm thick)

### 3 Electrical characteristics

at  $T_j=25\text{ °C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	60	-	-	V	$V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$
Gate threshold voltage	$V_{GS(th)}$	1.2	1.7	2.2	V	$V_{DS}=V_{GS}$ , $I_D=28\text{ }\mu\text{A}$
Zero gate voltage drain current	$I_{DSS}$	-	0.1 5.0	1.0 100	$\mu\text{A}$	$V_{DS}=60\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ °C}$ $V_{DS}=60\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ °C}$
Gate-source leakage current	$I_{GSS}$	-	-	100	nA	$V_{GS}=16\text{ V}$ , $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	9.5 12.5	11.2 15.8	m $\Omega$	$V_{GS}=10\text{ V}$ , $I_D=17\text{ A}$ $V_{GS}=4.5\text{ V}$ , $I_D=10\text{ A}$

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance <sup>1)</sup>	$C_{iss}$	-	3090	4020	pF	$V_{GS}=0\text{ V}$ , $V_{DS}=30\text{ V}$ , $f=1\text{ MHz}$
Output capacitance <sup>1)</sup>	$C_{oss}$	-	590	770	pF	$V_{GS}=0\text{ V}$ , $V_{DS}=30\text{ V}$ , $f=1\text{ MHz}$
Reverse transfer capacitance <sup>1)</sup>	$C_{rss}$	-	28	56	pF	$V_{GS}=0\text{ V}$ , $V_{DS}=30\text{ V}$ , $f=1\text{ MHz}$
Turn-on delay time	$t_{d(on)}$	-	11	-	ns	$V_{DD}=30\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ , $R_{G,ext}=11\text{ }\Omega$
Rise time	$t_r$	-	3	-	ns	$V_{DD}=30\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ , $R_{G,ext}=11\text{ }\Omega$
Turn-off delay time	$t_{d(off)}$	-	51	-	ns	$V_{DD}=30\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ , $R_{G,ext}=11\text{ }\Omega$
Fall time	$t_f$	-	7	-	ns	$V_{DD}=30\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ , $R_{G,ext}=11\text{ }\Omega$

**Table 6 Gate charge characteristics<sup>2)</sup>**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{gs}$	-	10	13	nC	$V_{DD}=30\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$
Gate to drain charge	$Q_{gd}$	-	3.4	6.7	nC	$V_{DD}=30\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$
Gate charge total	$Q_g$	-	41	55	nC	$V_{DD}=30\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$
Gate plateau voltage	$V_{plateau}$	-	3.2	-	V	$V_{DD}=30\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$

<sup>1)</sup> Defined by design. Not subject to production test.

<sup>2)</sup> See "Gate charge waveforms" for parameter definition. Defined by design, not subject to production test

**Table 7 Reverse diode**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	$I_S$	-	-	38	A	$T_C=25\text{ °C}$
Diode pulse current	$I_{S,pulse}$	-	-	228	A	$T_C=25\text{ °C}$
Diode forward voltage	$V_{SD}$	-	0.88	1.1	V	$V_{GS}=0\text{ V}, I_F=17\text{ A}, T_j=25\text{ °C}$
Reverse recovery time	$t_{rr}$	-	35	-	ns	$V_R=30\text{ V}, I_F=9\text{ A}, di_F/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	$Q_{rr}$	-	35	-	nC	$V_R=30\text{ V}, I_F=9\text{ A}, di_F/dt=100\text{ A}/\mu\text{s}$

### 4 Electrical characteristics diagrams

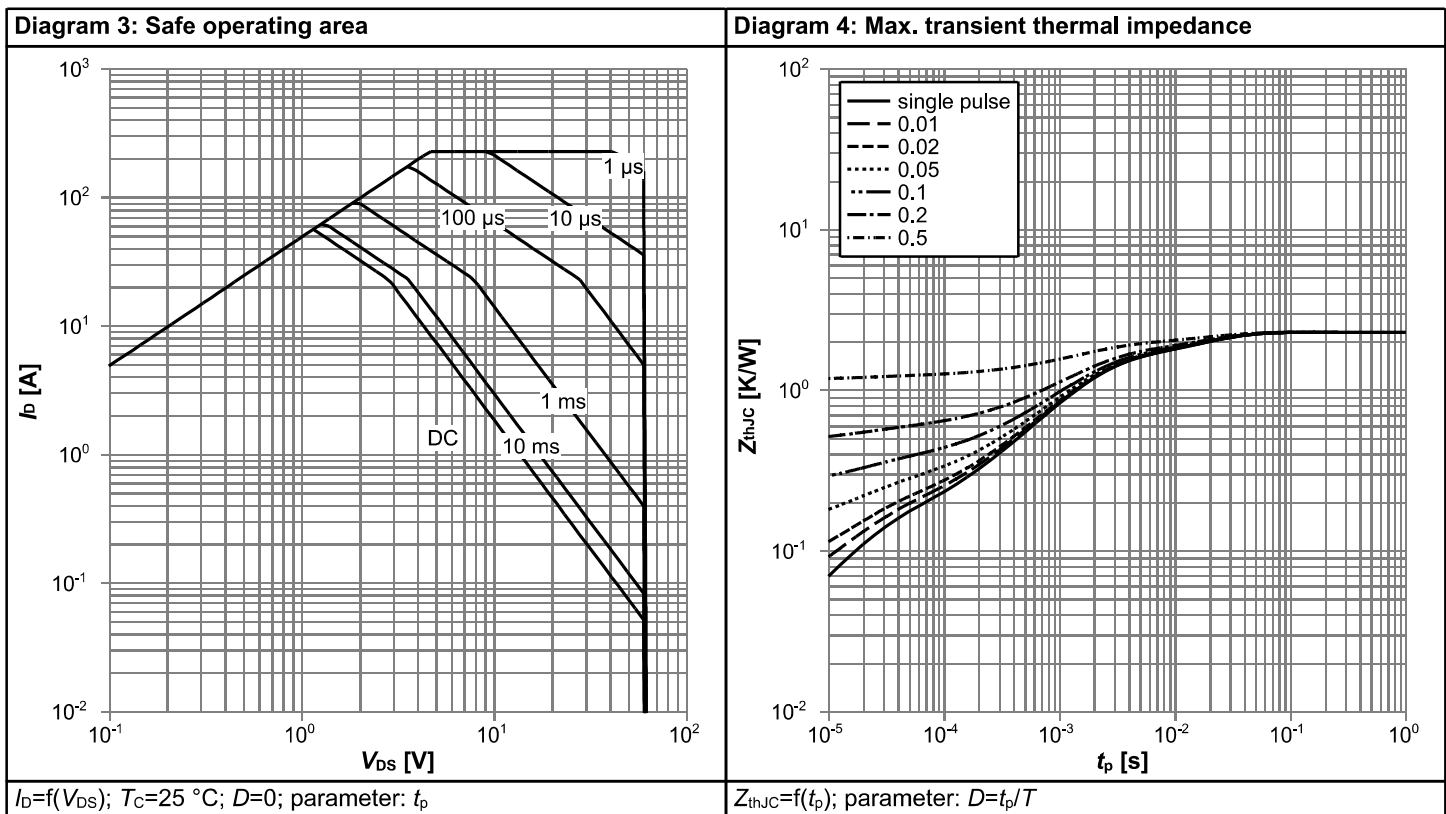
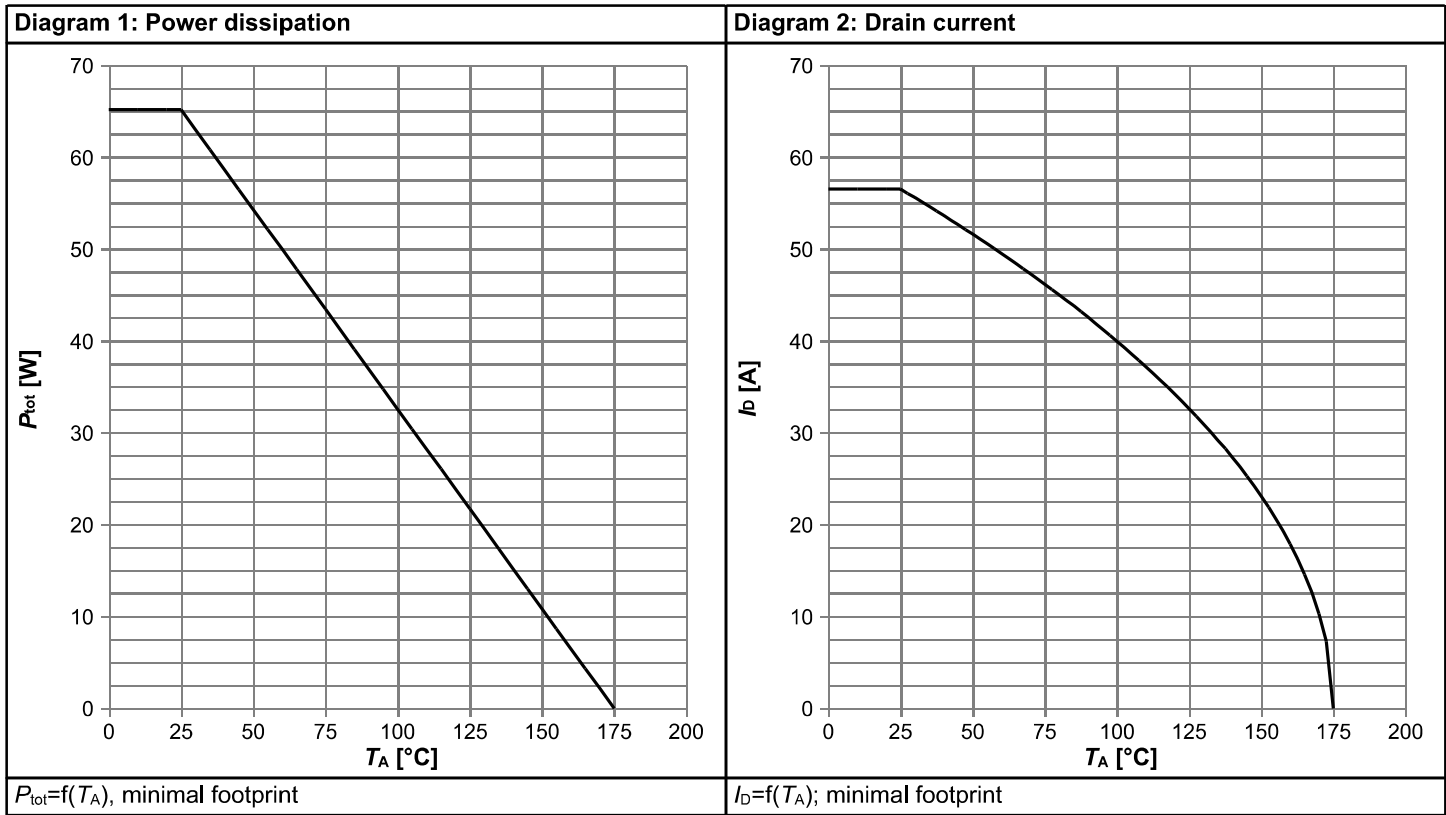
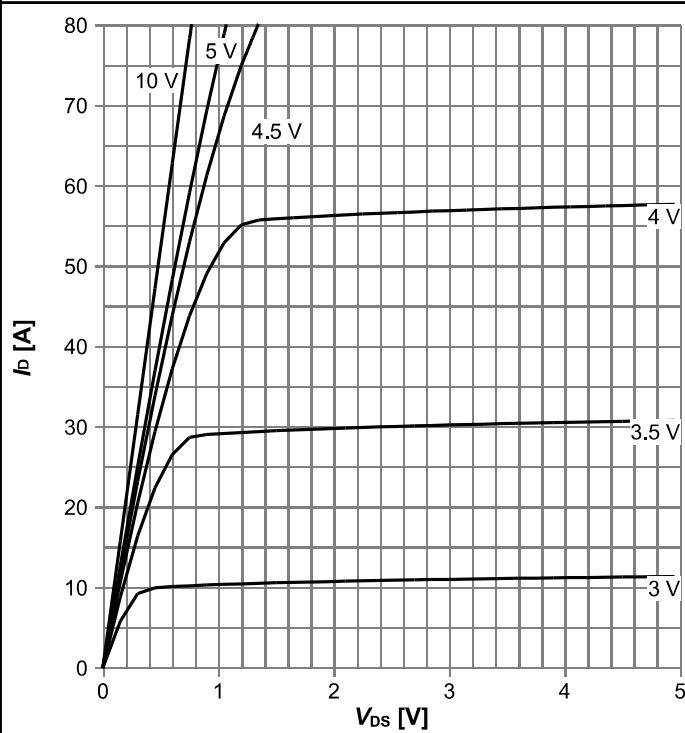
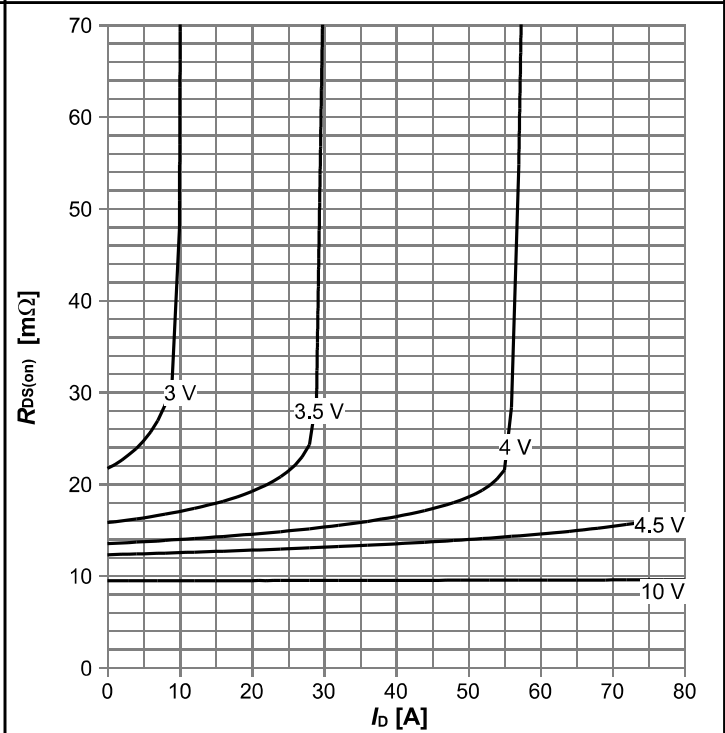


Diagram 5: Typ. output characteristics



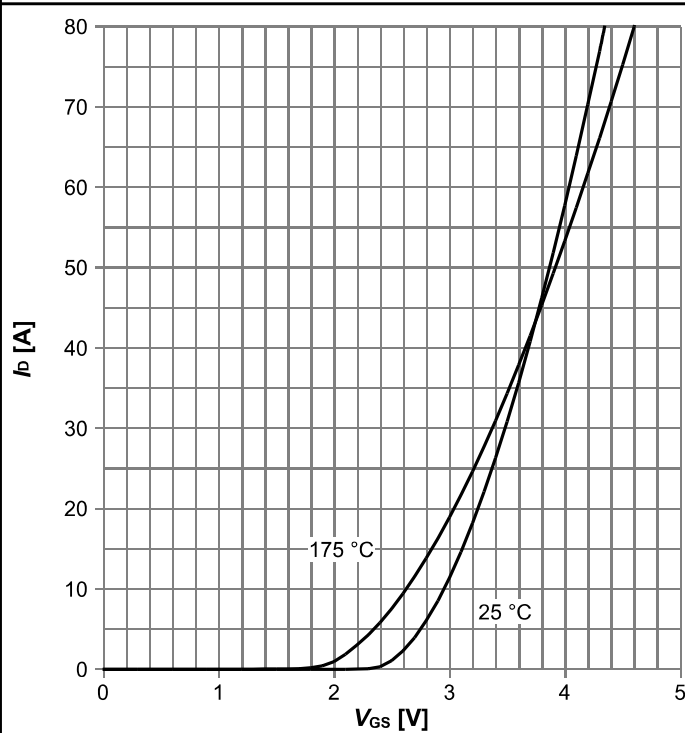
$I_D = f(V_{DS}), T_j = 25^\circ\text{C};$  parameter:  $V_{GS}$

Diagram 6: Typ. drain-source on resistance



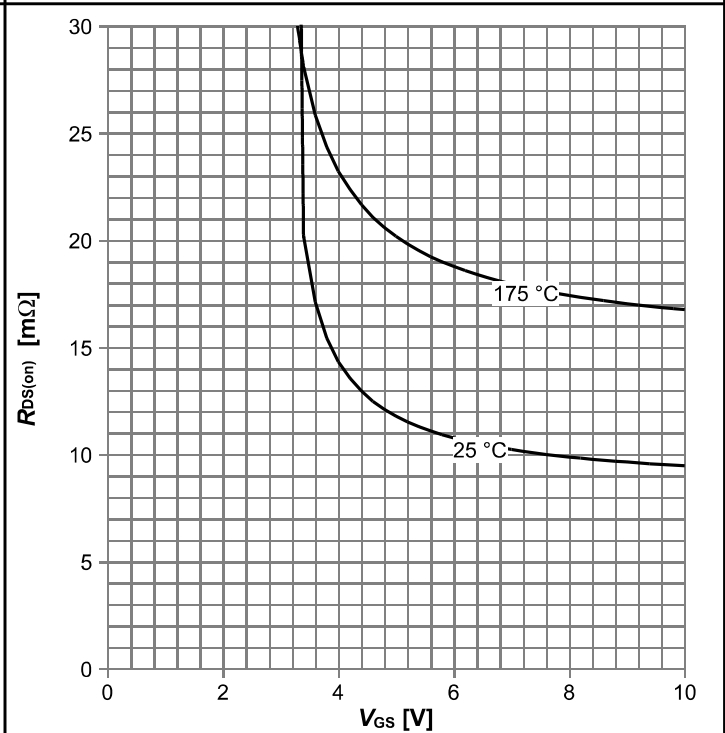
$R_{DS(on)} = f(I_D), T_j = 25^\circ\text{C};$  parameter:  $V_{GS}$

Diagram 7: Typ. transfer characteristics



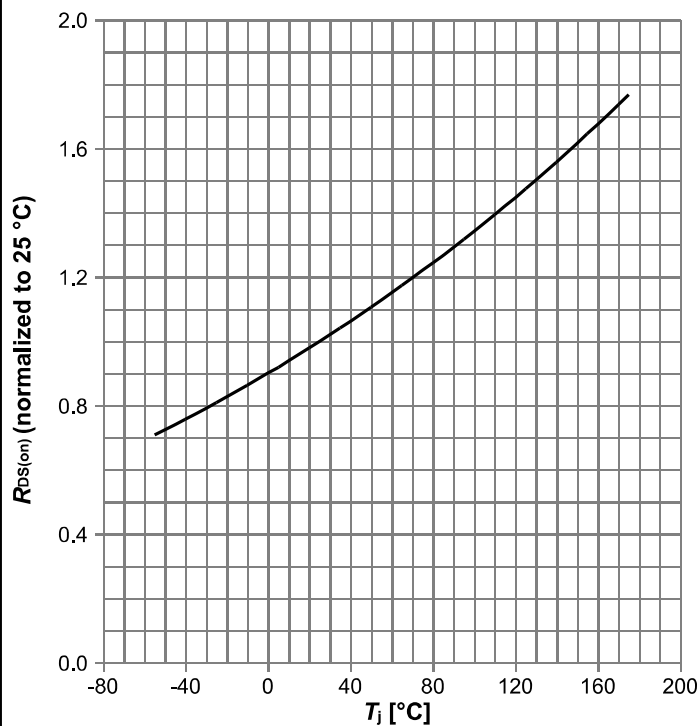
$I_D = f(V_{GS}), |V_{DS}| > 2|I_D|R_{DS(on)max};$  parameter:  $T_j$

Diagram 8: Typ. drain-source on resistance



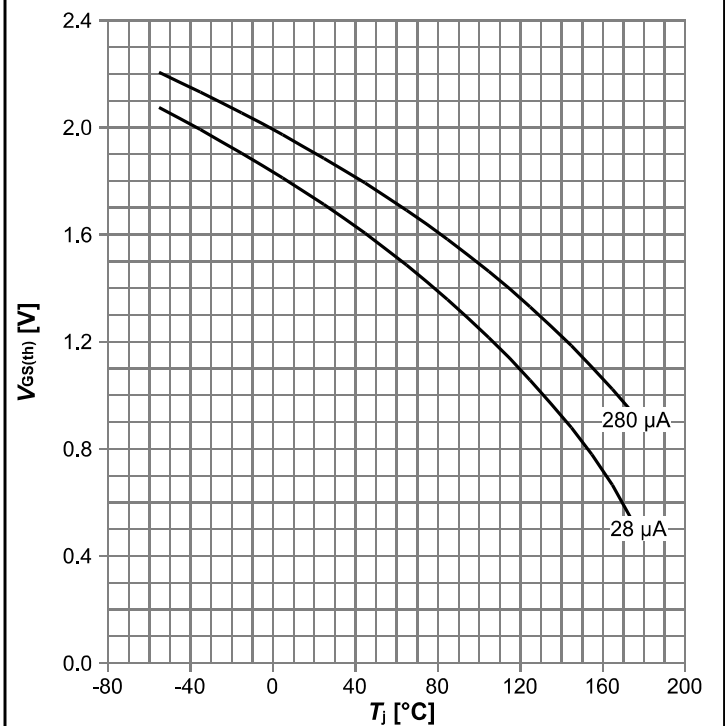
$R_{DS(on)} = f(V_{GS}), I_D = 17\text{ A};$  parameter:  $T_j$

Diagram 9: Normalized drain-source on resistance



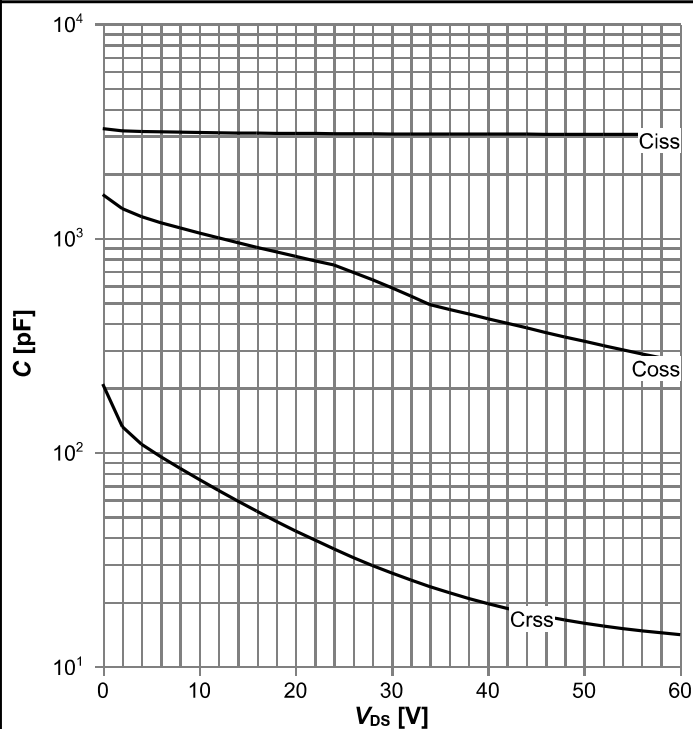
$R_{DS(on)}=f(T_j)$ ,  $I_D=17$  A,  $V_{GS}=10$  V

Diagram 10: Typ. gate threshold voltage



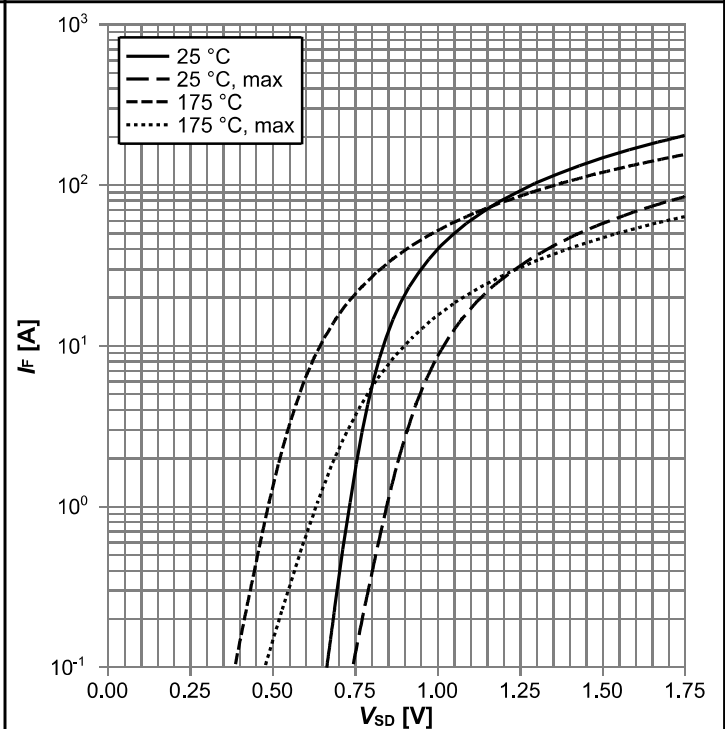
$V_{GS(th)}=f(T_j)$ ,  $V_{GS}=V_{DS}$ ; parameter:  $I_D$

Diagram 11: Typ. capacitances



$C=f(V_{DS})$ ;  $V_{GS}=0$  V;  $f=1$  MHz

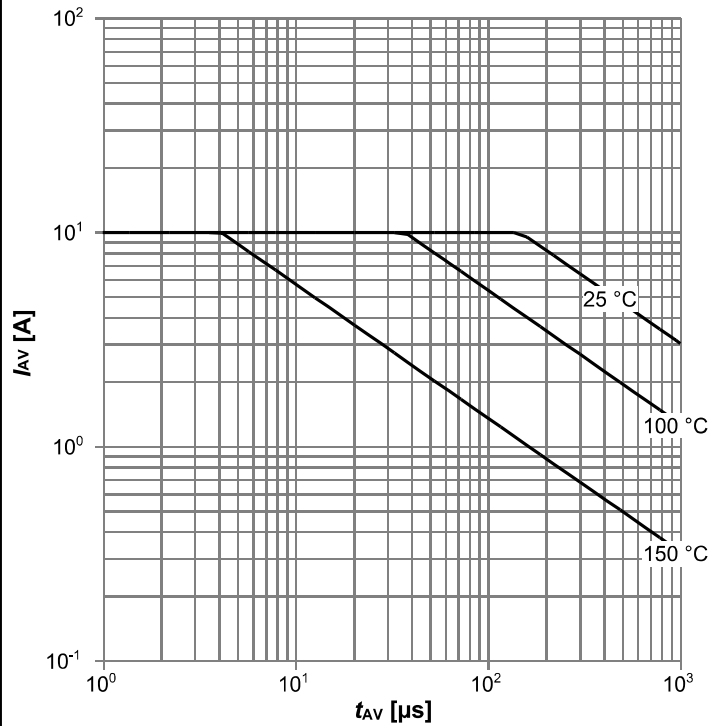
Diagram 12: Forward characteristics of reverse diode



$I_F=f(V_{SD})$ ; parameter:  $T_j$

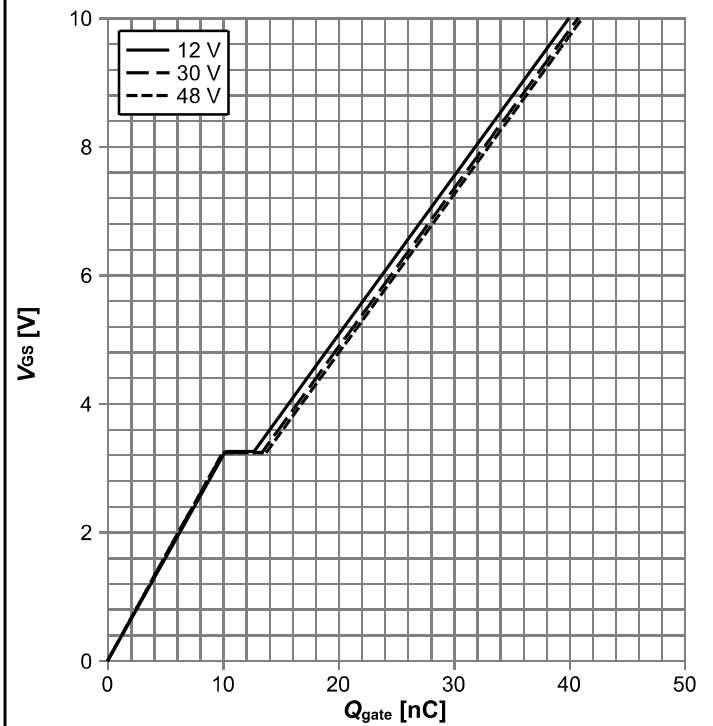


**Diagram 13: Avalanche characteristics**



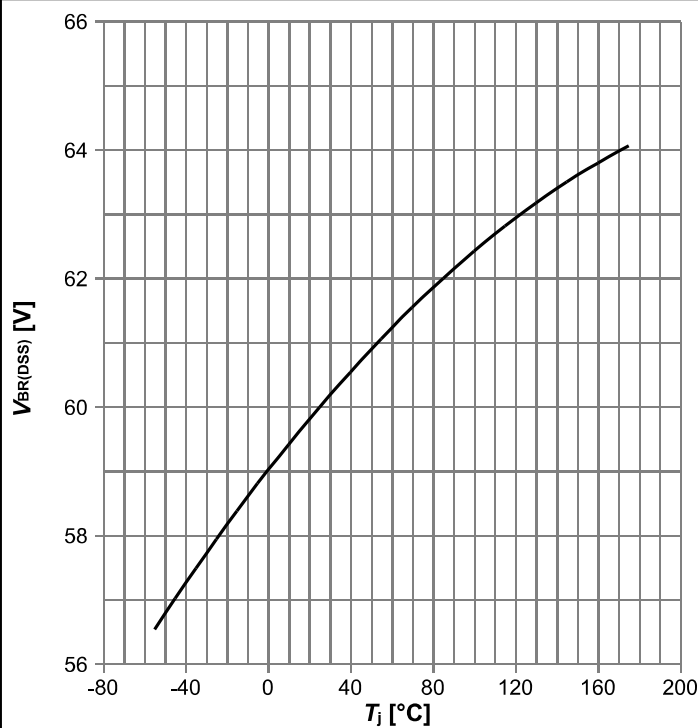
$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$ ; parameter:  $T_{j,start}$

**Diagram 14: Typ. gate charge**



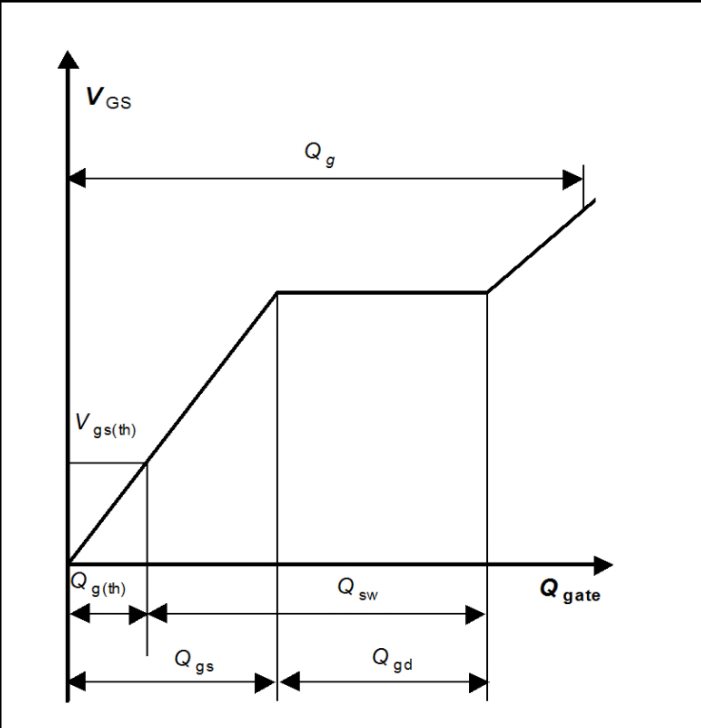
$V_{GS}=f(Q_{gate}), I_D=20 \text{ A pulsed}, T_j=25 \text{ °C}$ ; parameter:  $V_{DD}$

**Diagram 15: Drain-source breakdown voltage**

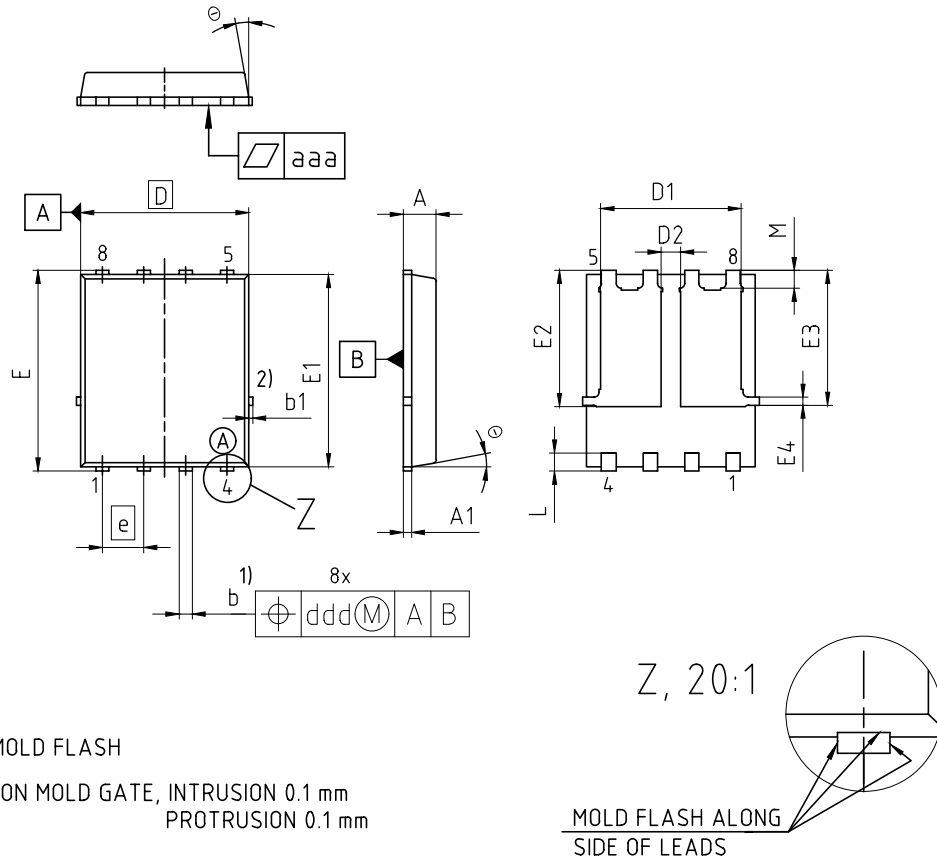


$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$

**Diagram Gate charge waveforms**



## 5 Package Outlines



- 1) EXCLUDE MOLD FLASH
- 2) REMOVAL ON MOLD GATE, INTRUSION 0.1 mm  
PROTRUSION 0.1 mm

ALL METAL SURFACES ARE PLATED EXCEPT AREA OF CUT

DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	0.90	1.10
A1	0.15	0.35
b	0.34	0.54
b1	0.02	0.22
D	4.95	5.35
D1	4.20	4.40
D2	0.50	0.70
E	5.95	6.35
E1	5.70	6.10
E2	4.075	4.275
E3	4.035	4.235
E4	0.15	0.35
e	1.27	
L	0.45	0.65
M	0.45	0.65
ø	8.5°	11.5°
aaa	0.05	
ddd	0.10	

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Figure 1 Outline PG-TDSON-8-4, dimensions in mm

## Revision History

BSC112N06LD

**Revision: 2021-06-28, Rev. 2.1**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2018-12-11	Release of final version
2.1	2021-06-28	Update current rating, footnotes and Id Diagram 9

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